XBS304F11R-G

Schottky Barrier Diode, 3A, 40V Type

■FEATURES

Low Forward voltage Environmentally Friendly

: EU RoHS Compliant

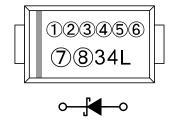
■ PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT		
XBS304F11R-G *	SMA-PG	1,800/Reel		

* The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant.

* The high-melting solder paste (lead-containing) is used as attachment.

■ MARKING



12345678: Control Number

■ APPLICATIONS

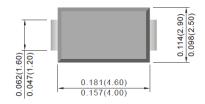
- Rectification
- Protection against reverse connection of battery

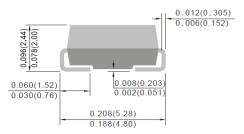
■ PACKAGING INFORMATION



Unit : inch (mm)

ETR16028-001





■ABSOLUTE MAXIMUM RATINGS

Ta=25℃

	-	-	-	
PARAMETER	SYMBOL	RATINGS	UNITS	
Repetitive Peak Reverse Voltage	V _{RM}	40	V	
Reverse Voltage (DC)	V _R 40		V	
Forward Current (Average) at Ta=75°C	I _{F(AV)} 3		А	
Non Continuous				
Forward Surge Current	I _{FSM}	50	A	
(8.3 ms single half-sine wave)				
Junction Temperature	Tj	125	°C	
Storage Temperature	Tstg	-55 to +150	°C	

ELECTRICAL CHARACTERISTICS

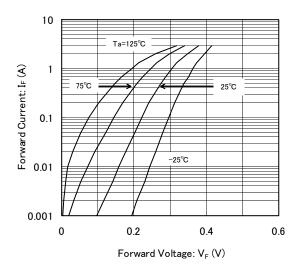
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			
			MIN.	TYP.	MAX.	UNITS
Forward Voltage	V_{F1}	I _F =1A	-	-	0.35	V
	V_{F2}	I _F =3A	-	-	0.45	V
Reverse Current	I _{R1}	V _R =20V			1	mA
	I _{R2}	V _R =40V			2	mA

Ta=25°C

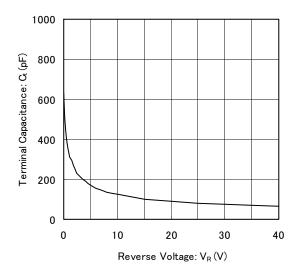
XBS304F11R-G

■ TYPICAL PERFORMANCE CHARACTERISTICS

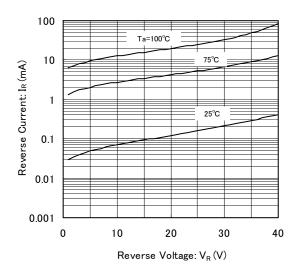
(1) Forward Current vs. Forward Voltage



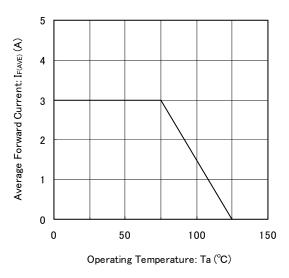
(3) Terminal Capacitance vs. Reverse Voltage



(2) Reverse Current vs. Reverse Voltage



(4) Average Forward Current vs. Operating Temperature



■NOTES ON USE

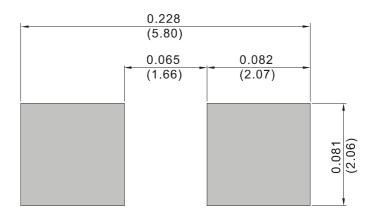
Please use this IC within the absolute maximum ratings.
 Even within the ratings, in case of high load use continuously such as high temperature, high voltage, high current and thermal stress may cause reliability degradation of the IC.

2. Torex places an importance on improving our products and their reliability. We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

■REFERENCE PATTERN LAYOUT

●SMA-PG

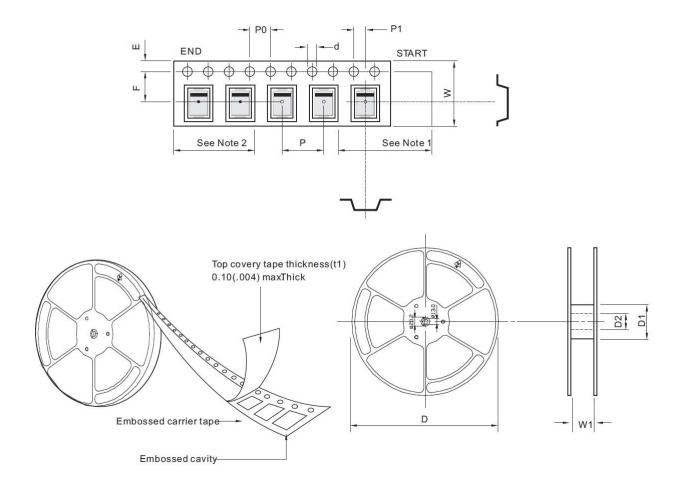
Unit : inch (mm)



XBS304F11R-G

■TAPING SPECIFICATIONS

●SMA-PG



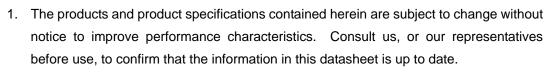
Note:

1. There shall be leader of 230mm minimum which may consist of carrier and or cover tape follower by a minimum of

160mm of carrier tape sealded with cover tape.

2. There shall be minimum of 160mm of empty component pockets sealded with cover tape.

SYMBOL	mm
d	1.55 ± 0.05
D	178.0 ± 2.0
D1	min. 50.0
D2	13.0 ± 0.2
E	1.75 ± 0.10
F	5.50 ± 0.10
Р	4.00 ± 0.10
P0	4.00 ± 0.10
P1	2.00 ± 0.10
W	12.0 ± 0.3
W1	13.4 ± 1.0



- 2. We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.
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- The products in this datasheet are not developed, designed, or approved for use with such equipment whose failure of malfunction can be reasonably expected to directly endanger the life of, or cause significant injury to, the user.
 (e.g. Atomic energy; aerospace; transport; combustion and associated safety
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 Should you wish to use the products under conditions exceeding the specifications, please consult us or our representatives.
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